ON Semiconductor®

Final Product/Process Change Notification

Document #:FPCN23582Y
Issue Date:02 Mar 2021

Title of Change:	Replace Hitachi mold compound with Hysol compound for Medical devices at Leshan, China
Proposed First Ship date:	09 Jun 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Sun Chengrong <c.r.sun@lps.com.cn> or Han Zhang <zbfftb@onsemi.com>
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or ffvf9f@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Products (listed in this PCN) assembled with Hysol compound in ON Semiconductor facility, Leshan, China, will have a Finish Good Date Code from about Week 21, 2021 or greater
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
Leshan Phoenix Semiconductor, China	None

Description and Purpose:

Changing description is listed in below table.

Reliability Qualification and electrical characterization will be performed during qualification, and can be shared after issuing Final PCN.

	Before Change Description	**After Change Description**
Mold Compound	Hitachi GE200F	Hysol GR640 HV

There is no product marking change as a result of this change.

Reliability Data Summary:

QV DEVICE NAME: **0IMD4-001-XTP, MDNSD16F3T5G, 0IMT1 001-XTP, 0IMDD-001-XTP , 0IMD1-001-XTP, 0IMD6-001-XTP**
RMS# **: L69382, L69381, L69380, L69378, L72378, L71464**
PACKAGE: **: SOT563,SOD1123,SC74,SC70,SOD923,SOT723**

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2min	15000 cyc	0/231
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	-
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 5 sec		0/30

Electrical Characteristics Summary:

Electrical characteristics are not impacted, details can be provided upon customer request.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
0IMD1-001-XTP	0IMD1-001-XTP
0IMD6-001-XTP	0IMD6-001-XTP
MDNSD16F3T5G	MDNSD16F3T5G